

HMC788A Die Revision, Assembly Site, Marking and Material Change

HMC788A Qualification Results Summary

| QUALIFICATION PLAN / STATUS | | | |
|--|----------------------------|------------------|---------------------------|
| TEST | SPECIFICATION | SAMPLE SIZE | RESULTS |
| Temperature Cycle (TC)* | JEDEC <i>JESD22-A104</i> | 3x25 | Pass |
| High Temperature Storage Life (HTSL) | JEDEC <i>JESD22-A103</i> | 1x77 | Pass |
| Solder Heat Resistance (SHR)* | JEDEC/IPC <i>J-STD-020</i> | 3x25 | Pass |
| Electrostatic Discharge <i>Human Body Model</i> | ESDA/JEDEC <i>JS-001</i> | 3/voltage | Pass <u>±</u>250V |
| Electrostatic Discharge <i>Field-Induced Charged Device Model</i> | JEDEC <i>JESD22-C101</i> | 3/voltage | Pass <u>±</u>1000V |

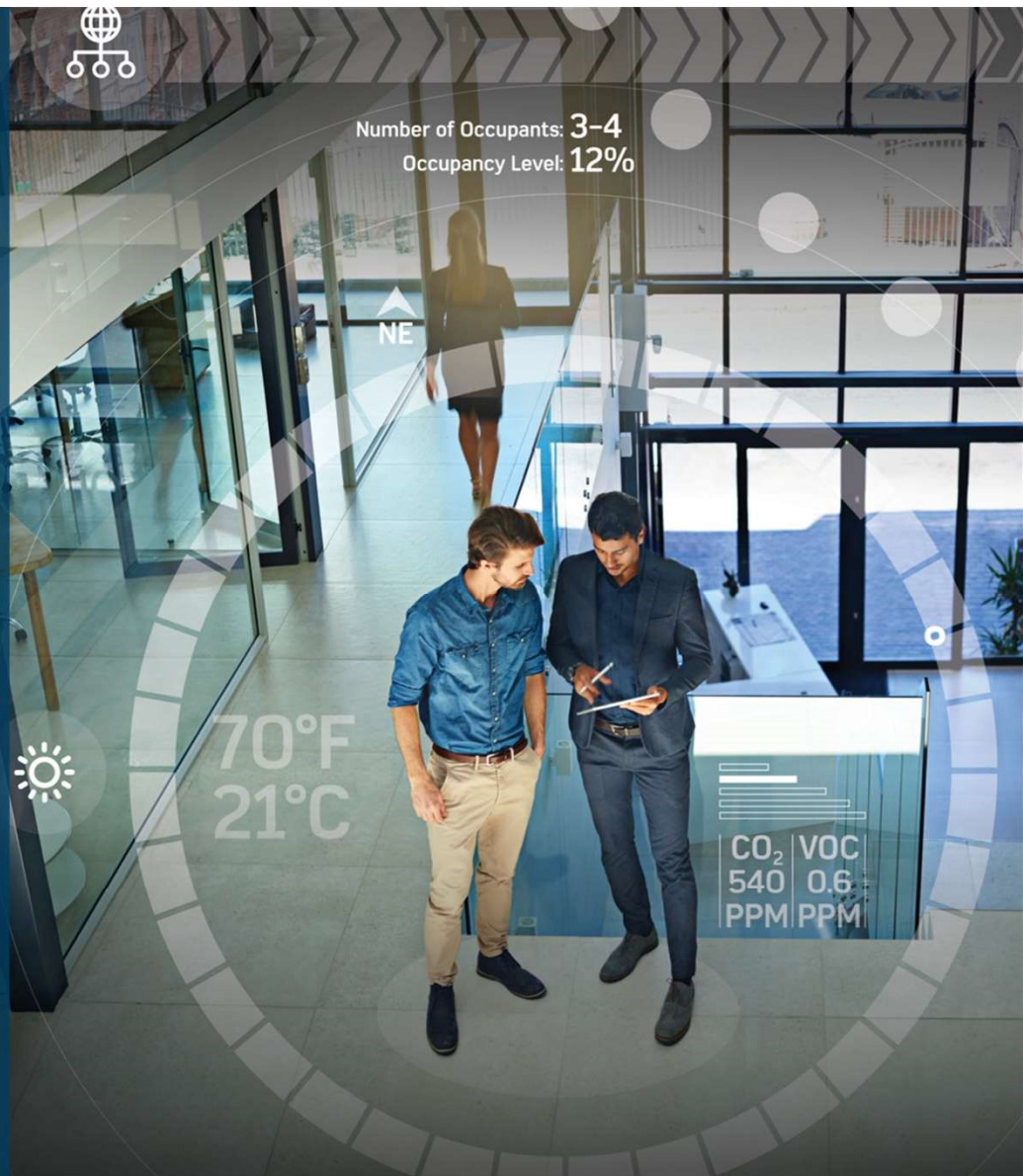
* These samples were subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125°C, Unbiased Soak: 192 hrs @ 30°C, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260°C.



AHEAD OF WHAT'S POSSIBLE™

HMC788A Die Revision, Assembly Site, Marking Code and Material Change

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Detailed Change Description

Commercial Part

| Parameter | Current | GoTo |
|------------------------|--------------------------------|------------------------------|
| Die rev. – via removal | No | Yes |
| Assembly Site | Unisem (UG1) | ASE (AEK) |
| Lead Frame | 100Sn | Ni-Pd-Au |
| Die Attach | Sumitomo CRM 1076DJ conductive | Hitachi EN 4900GC conductive |
| Mold Compound | Sumitomo G770HCD | Sumitomo G700LYT |
| Wire diameter (mils) | 1.0 | 0.8 |
| Marking Code | 788A | Y7H |